

N-Channel Enhancement Mode Field Effect Transistor

● Features

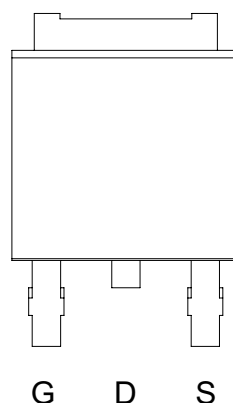
V_{DS} 60V, V_{GS} 20V, I_D 18A,

$R_{DS(ON)} < 40m\Omega$ @ $V_{GS} = 10V$

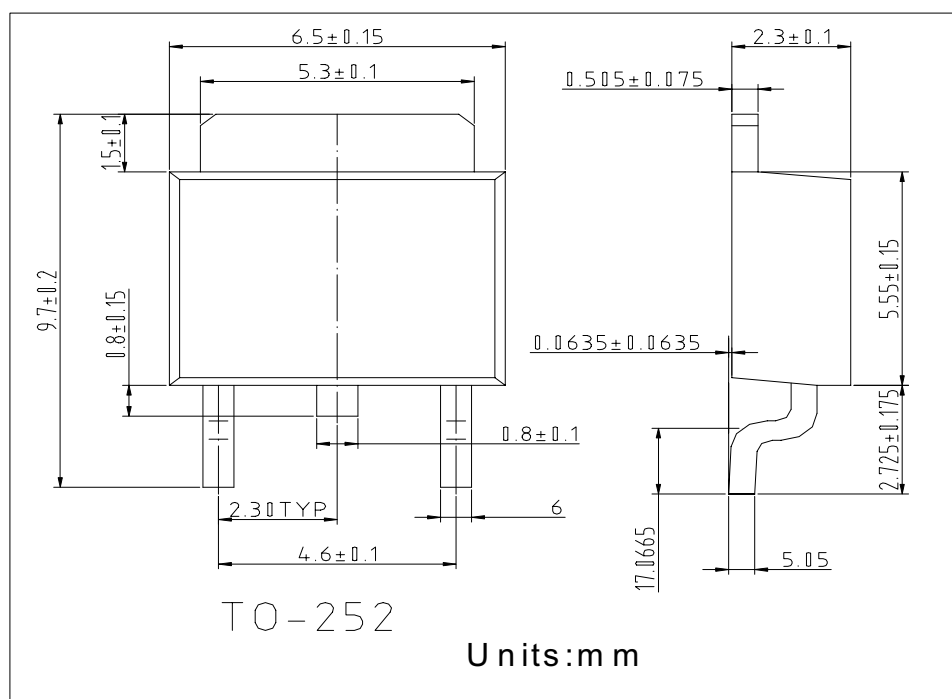
● General Description

This device has specifically been designed to minimize input capacitance and gate charge. It is therefore suitable as primary switch in advanced high-efficiency isolated DC-DC converters for Telecom and Computer application. It is also intended for any application with low gate charge drive requirements.

● Pin Configurations



● Package Information



**● Absolute Maximum Ratings @T_A=25°C unless otherwise noted**

Parameter	Symbol	Ratings	Unit
Drain-Source Voltage	V _{DSS}	60	V
Gate-Source Voltage	V _{GSS}	±20	V
Maximum Drain Current - Continuous	I _D	18	A
- Pulsed		45	
Continuous Power Dissipation(large heatsink)	P _D	110	W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to 150	°C

● Electrical Characteristics @T_A=25°C unless otherwise noted

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0 V, I _D = 250 μA	60	--	--	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 60 V, V _{GS} = 0 V	--	--	1	μA
Gate - Body Leakage	I _{GSS}	V _{GS} = ±20 V, V _{DS} = 0 V	--	--	±100	nA
ON CHARACTERISTICS ^b						
Gate Threshold Voltage	V _{GS (th)}	V _{DS} = V _{GS} , I _D = 250 μA	1.1	1.5	2.9	V
Static Drain-Source On-Resistance	R _{DS(ON)}	V _{GS} = 10 V, I _D = 10 A	--	35	40	mR
		V _{GS} = 4.5 V, I _D = 5 A	--	42	50	
Forward Transconductance	g _{FS}	V _{DS} = 15 V, I _D = 10 A	--	20	--	S
DYNAMIC CHARACTERISTICS						
Input Capacitance	C _{iss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1MHz	--	1000	--	pF
Output Capacitance	C _{oss}		--	200	--	
Reverse Transfer Capacitance	C _{rss}		--	100	--	
SWITCHING CHARACTERISTICS ^b						
Turn-On Delay Time	t _{d(on)}	V _{DS} = 30 V, I _D = 10 A V _{GS} = 10 V, R _{gen} =4.7 Ω	--	45		ns
Turn-On Rise Time	t _r		--	22		
Turn-Off Delay Time	t _{d(off)}		--	42		
Turn-Off Fall Time	t _f		--	13		
Total Gate Charge	Q _g	V _{DS} = 48 V, I _D = 18 A V _{GS} = 10 V	--	50		nC
Gate–Source Charge	Q _{gs}		--	20	--	
Gate–Drain Charge	Q _{gd}		--	15	--	
DRAIN-SOURCE DIODE CHARACTERISTICS AND MAXIMUM RATINGS ^b						
Drain–Source Diode Forward Voltage	V _{SD}	V _{GS} = 0 V, I _S = 18 A ⁽²⁾	--	--	1.3	V

Note:

1. R_{θJA} is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. R_{θJC} is guaranteed by design while R_{θCA} is determined by the user's board design.
2. Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2.0%

Typical Performance Characteristics

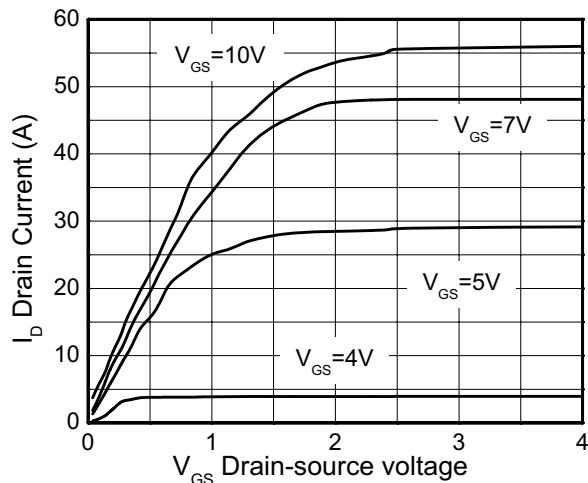


Fig1. Drain Current vs. Drain-Source Voltage

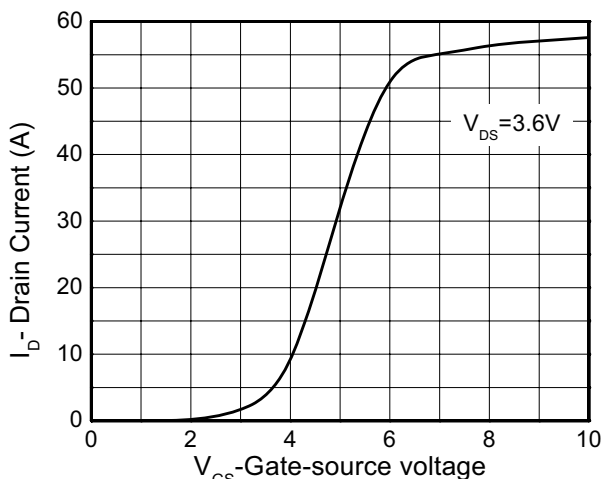


Fig2. Drain Current vs. Gate-Source Voltage

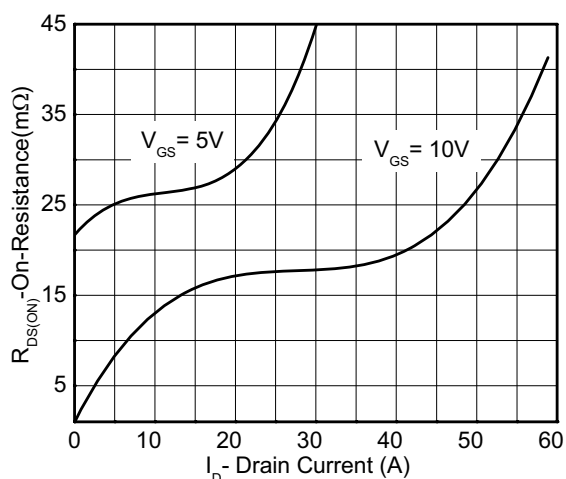


Fig3. On-Resistance vs. Drain Current

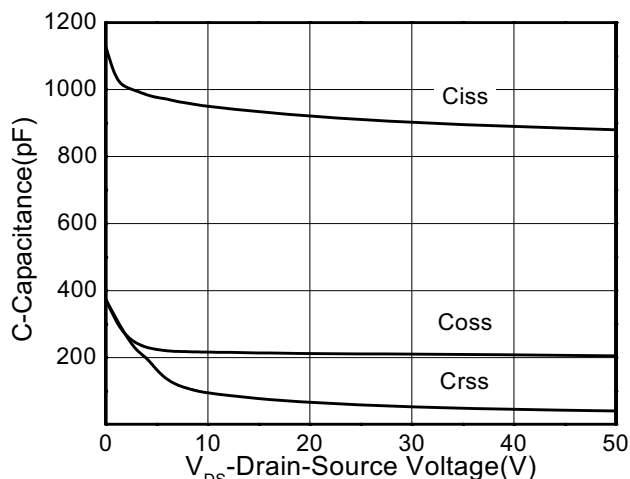


Fig4. Drain-Source Voltage vs. Capacitance

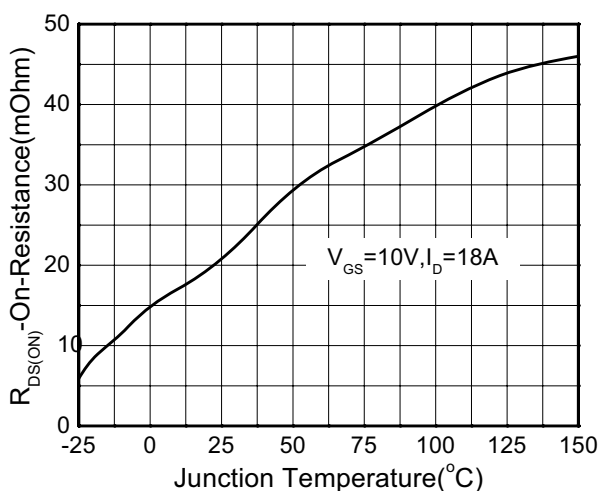


Fig5. On-Resistance vs. Junction Temperature

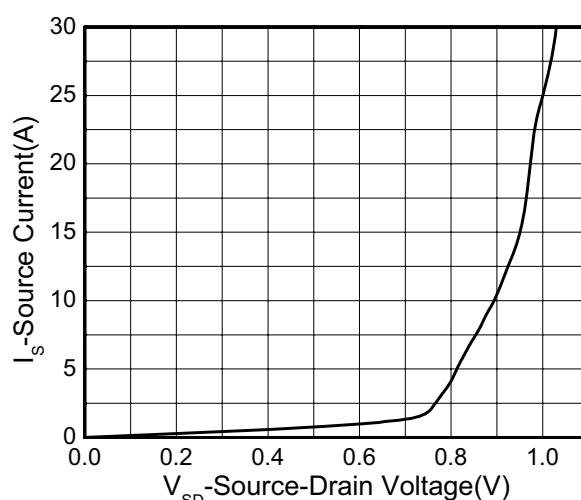
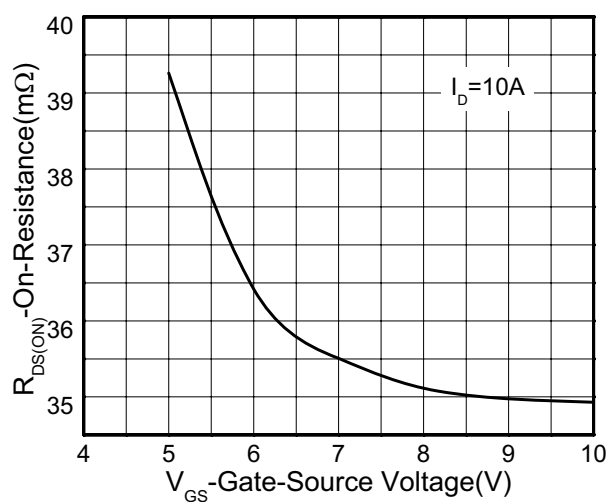
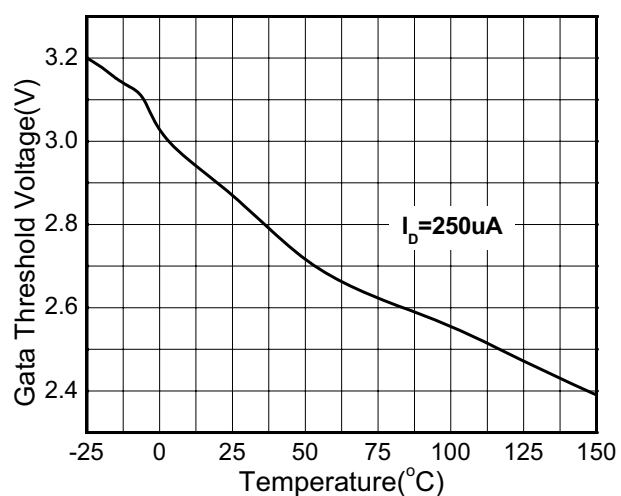


Fig6. Body Diode Forward Voltage vs Diode Current


Fig7. On-Resistance vs. Gate-Source Voltage

Fig8. Gate Threshold Voltage vs Temperature



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